## **ABSTRACT**

A semiconductor device includes a semiconductor chip provided with an integrated circuit and a pad that is electrically connected to the integrated circuit. A wiring layer has a concave portion and is electrically connected to the pad. An external terminal is joined to the concave portion of the wiring layer. A resin layer is provided with a through hole and is disposed on the wiring layer. The through hole and the concave portion reside at the same position.

SEC/PatentProsecution/F009423/F009423US00.spec3.doc